

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. – 15. (Canceled)

16. (currently amended) A plastic injected part ~~according to claim 15, in which~~ with a printed circuit board that exhibits at least one contact element for connecting a mating contact, where the contact element is secured to the circuit board, and a plastic layer, which is applied to at least one side of the circuit board, where the contact element runs from the circuit board through the plastic layer and projects from this plastic layer to connect the mating contact,
characterized in that

the plastic extends from the plastic layer outward and laterally as ~~the~~ a pot shaped housing wall of a housing, and

the plastic layer and the housing wall are produced from the same material.

17. (original) A plastic injected part according to claim 15, in which
the plastic layer is applied to one or both sides of the circuit board,
in which the plastic layer is a thermoplastic material with a melting point greater than 80° C., particularly greater than 350° C.,
in which the contact element is soldered to the circuit board,
in which the circuit board consists of an epoxide fiberglass laminate with an interlaced resin system, and
in which at least one conductor is positioned on the surface of the circuit board and the plastic layer covers the conductor and an adjacent surface area of the circuit board.

18. – 20. (Canceled)